Features

- Uses CRM(CQ) advanced SkyMOS2 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent Q_gx$R_{DS(on)}$ product(FOM)
- AEC-Q101 Qualified

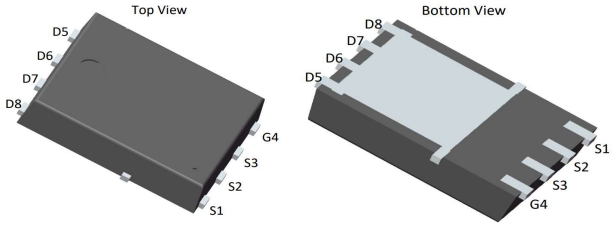
Product Summary

V_{DS}	60V
$R_{DS(on).typ}$	10mΩ
I_D	40A

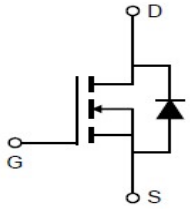
100% DVDS Tested
100% Avalanche Tested

Applications

- DCDC Converter
- Switching applications
- UPS (Uninterrupible Power Supplies)



CRSM120N06L2Q



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRSM120N06L2Q	120N06L2Q	PDFN5*6	Tape&reel	N/A	N/A	4000pcs

Absolute Maximum Ratings

Parameter	**Symbol**	**Value**	**Unit**
Drain-source voltage	V_{DS}	60	V
Continuous drain current T_C = 25°C (Silicon limit) T_C = 25°C (Package limit) T_C = 100°C (Silicon limit)	I_D	 40 40 28	A
Pulsed drain current (T_C = 25°C, t_p limited by T_{jmax})	$I_{D\ pulse}$	160	A
Avalanche energy, single pulse (IAS = 20A, Rg=25Ω)[1]	E_{AS}	60	mJ
Gate-Source voltage	V_{GS}	±20	V
Power dissipation (T_C = 25°C)	P_{tot}	37	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+175	°C
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	Tsold	260	°C

※. Notes:
EAS is tested at starting Tj = 25℃, L = 0.3mH, IAS =20A, VGS = 10V.

Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case (junction-heat spreader)	R_{thJC}	4.0	°C/W
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	52	

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Static Characteristic						
Drain-source breakdown voltage	BV_{DSS}	60	-	-	V	V_{GS}=0V, I_D=250uA
		60	-	-	V	V_{GS}=0V, I_D=1mA
Gate threshold voltage	$V_{GS(th)}$	1	-	2.5	V	V_{DS}=V_{GS},I_D=250uA
Zero gate voltage drain current	I_{DSS}	- -	- -	1 100	μA	V_{DS}=60V,V_{GS}=0V T_j=25°C T_j=125°C
Gate-source leakage current	I_{GSS}	-	-	±100	nA	V_{GS}=±20V,V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	-	10	13.0	mΩ	V_{GS}=10V, ID=20A
		-	15.0	20.0		V_{GS}=4.5V, ID=16A
Transconductance	g_{fs}	25	50	100	S	V_{DS}=5V,ID=20A
Dynamic Characteristic						
Input Capacitance	C_{iss}	480	960	1920	pF	V_{GS}=0V, V_{DS}=30V, f=1MHz
Output Capacitance	C_{oss}	135	270	540		
Reverse Transfer Capacitance	C_{rss}	-	14	100		
Gate Total Charge	Q_G	-	16	24	nC	V_{GS}=10V, V_{DS}=30V, I_D=20A,,f=1MHz
Gate-Source charge	Q_{gs}	-	5	20		
Gate-Drain charge	Q_{gd}	-	2.5	13		
Turn-on delay time	$t_{d(on)}$	-	7	13	ns	V_{GS}=10V, V_{DD}=30V, R_{G_ext}=2.7Ω
Rise time	t_r	-	30	45		
Turn-off delay time	$t_{d(off)}$	-	16	32		
Fall time	t_f	-	7	13		
Gate resistance	R_G	-	1.8	9	Ω	V_{GS}=0V, V_{DS}=0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.9	1.4	V	V_{GS}=0V,I_{SD}=20A
Body Diode Reverse Recovery Time	t_{rr}	29	57	115	ns	I_F=20A,dI/dt=300A/μs
Body Diode Reverse Recovery Charge	Q_{rr}	23	45	90	nC	

Typical Performance Characteristics

Fig 1: Output Characteristics

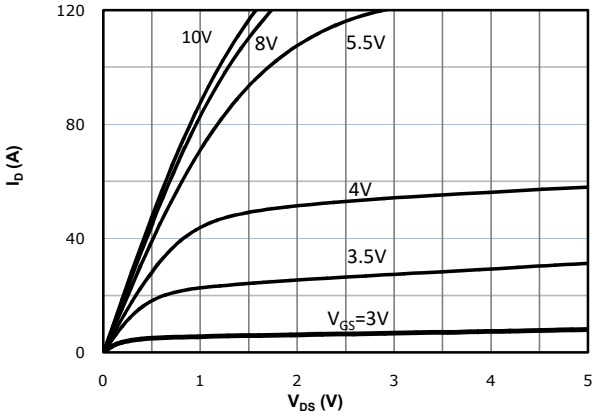


Fig 2: Transfer Characteristics

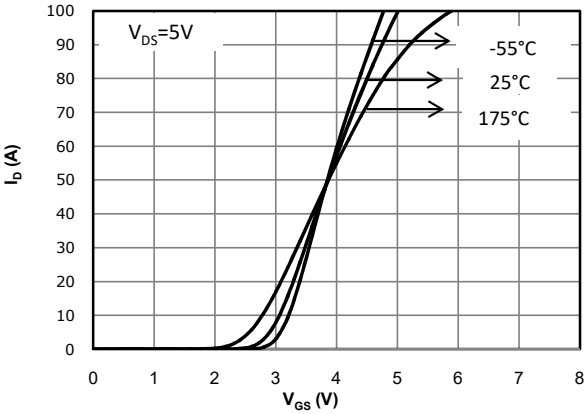


Fig 3: Rds(on) vs Drain Current and Gate Voltage

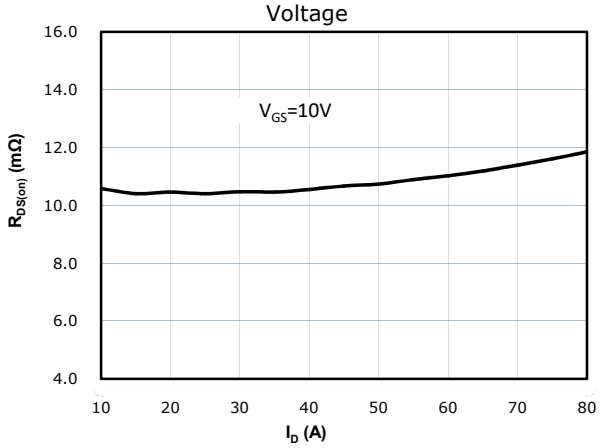


Fig 4: Rds(on) vs Gate Voltage

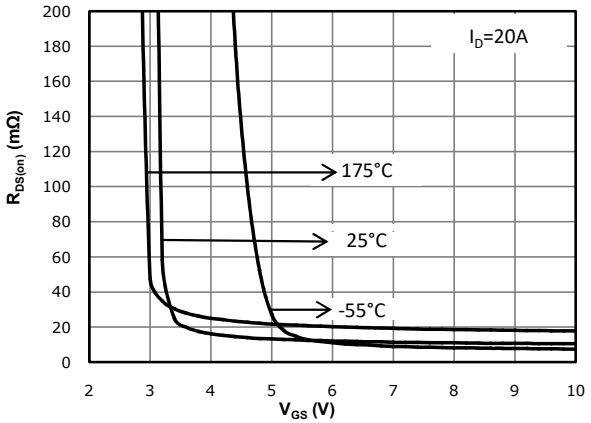


Fig 5: Rds(on) vs. Temperature

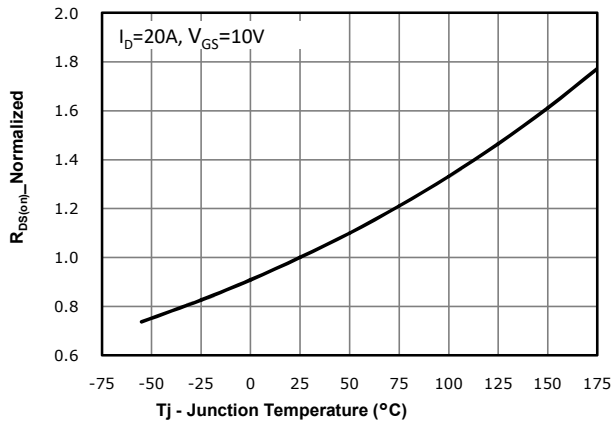


Fig 6: Vgs(th) vs. Temperature

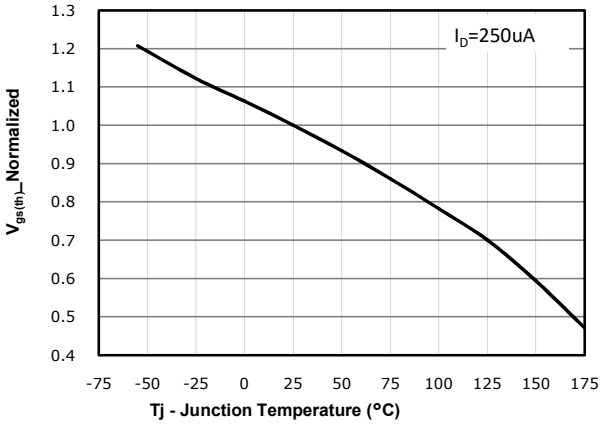


Fig 7: BVdss vs. Temperature

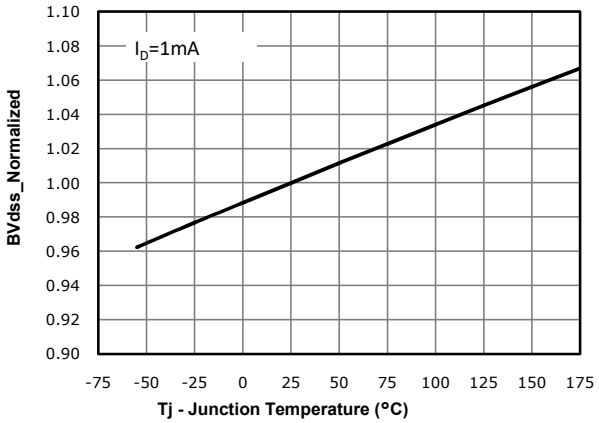


Fig 8: Capacitance Characteristics

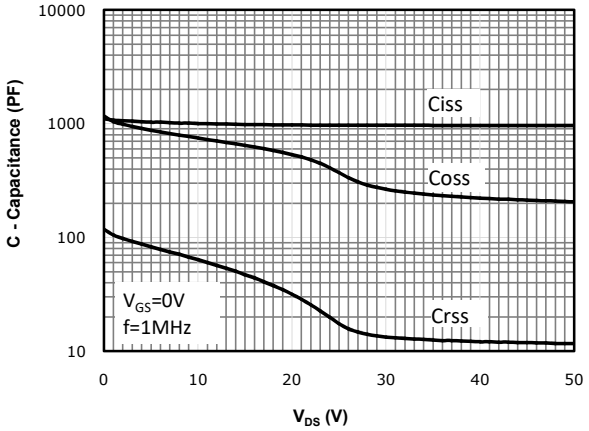


Fig 9: Gate Charge Characteristics

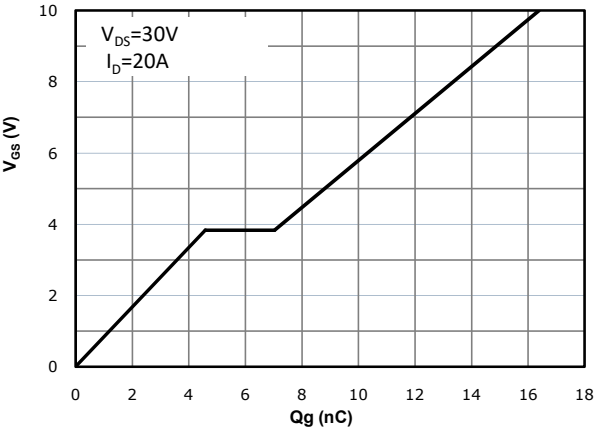


Fig 10: Body-diode Forward Characteristics

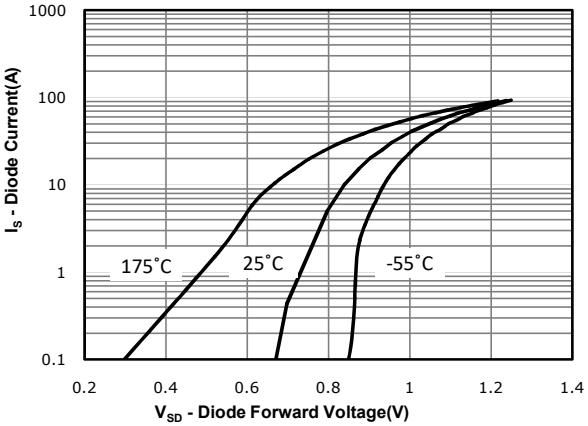


Fig 11: Power Dissipation

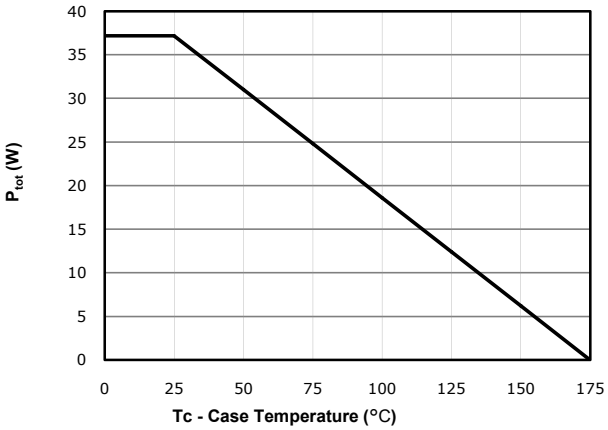


Fig 12: Drain Current Derating

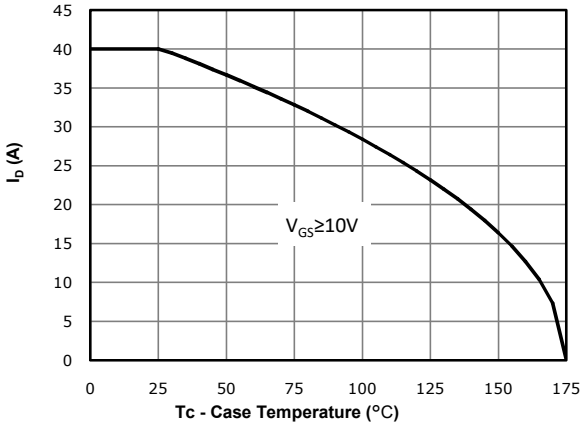


Fig 13: Safe Operating Area

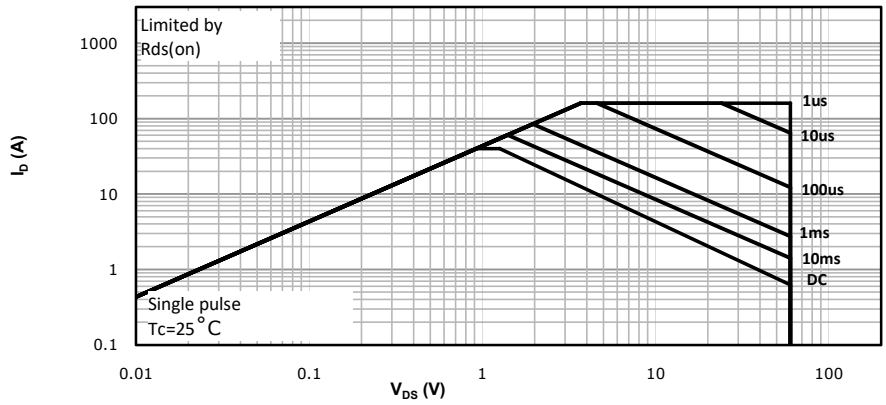
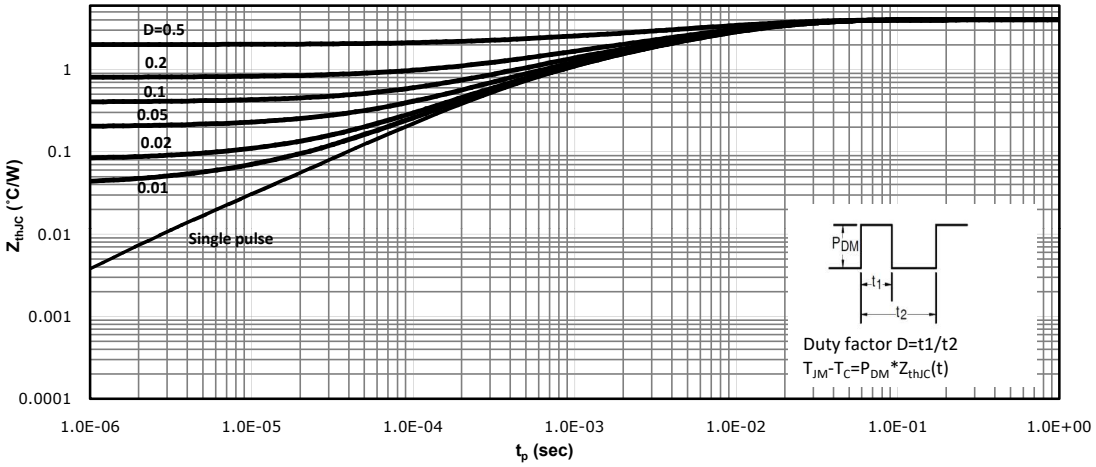
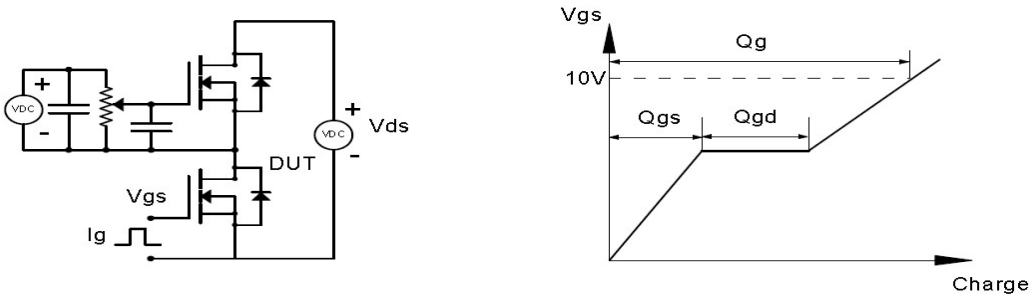


Fig 14: Max. Transient Thermal Impedance

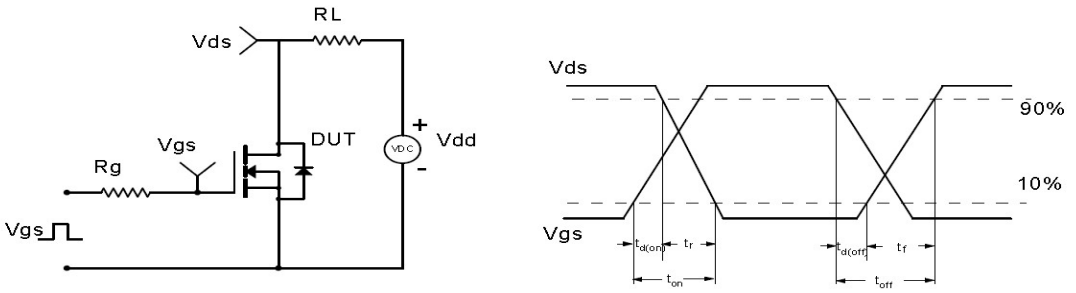


Test Circuit & Waveform

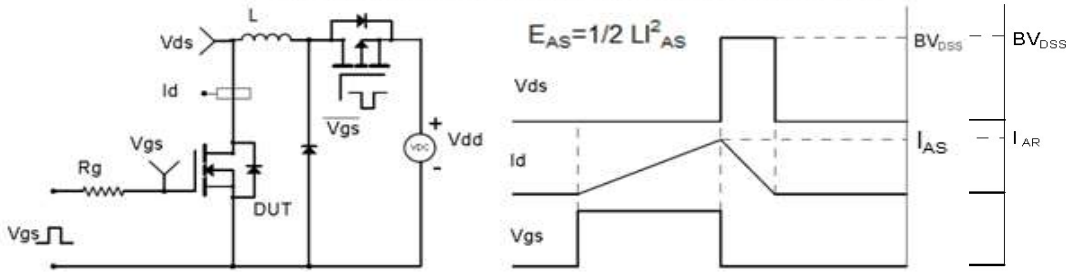
Gate Charge Test Circuit & Waveform



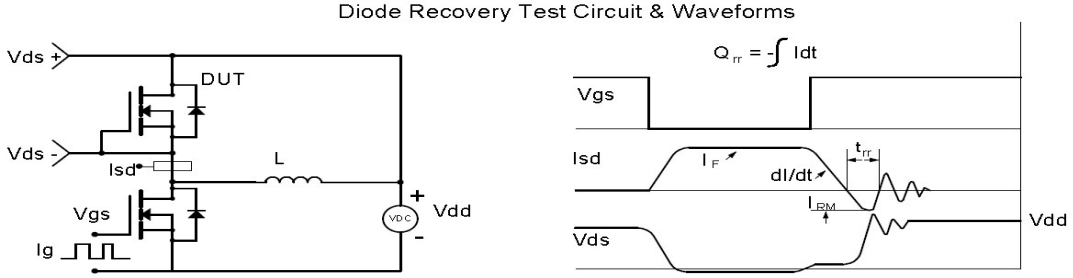
Resistive Switching Test Circuit & Waveforms



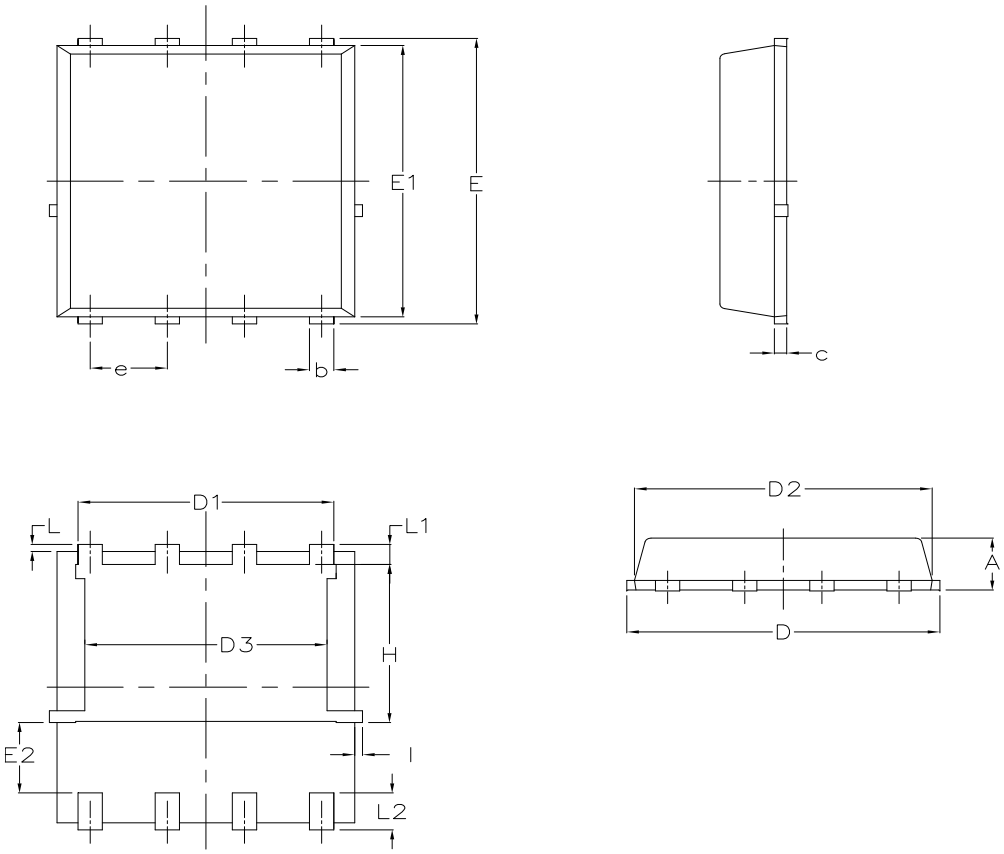
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: PDFN5x6 Type P



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min.	NOM.	Max.	Min.	NOM.	Max.
A	0.90	1.10	1.20	0.035	0.043	0.047
b	0.31	0.41	0.51	0.012	0.016	0.020
c	0.15	0.20	0.30	0.006	0.008	0.012
D	4.80	4.98	5.15	0.189	0.196	0.203
D1	3.91	4.22	4.36	0.154	0.166	0.172
D2	4.80	4.90	5.00	0.189	0.193	0.197
D3	3.85	4.00	4.15	0.152	0.157	0.163
E	5.90	6.05	6.15	0.232	0.238	0.242
E1	5.65	5.76	5.85	0.222	0.227	0.230
E2	1.10	-	-	0.043	-	-
e	1.27 BSC			0.050 BSC		
L	0.05	0.15	0.25	0.002	0.006	0.010
L1	0.38	0.43	0.50	0.015	0.017	0.020
L2	0.51	0.79	0.86	0.020	0.031	0.034
H	3.25	3.35	3.58	0.128	0.132	0.141
I	0.00	-	0.18	0.000	-	0.007

Marking

NOTE:	
XAAAAAAA-Y	
X	—Assembly location code
AAAAAAA	—Assembly lot NO. last 7digits
Y	—Bin code

Revision History

Revision	Date	Major changes
1.0	2023/11/13	Release of preliminary version.

Disclaimer

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